DERWENT-ACC-NO: 1985-071212

DERWENT-WEEK: 198512

TITLE: Resist pattern prodn. - by lithographic printing of circuit board, pinholes overprinting, and curing

PATENT-ASSIGNEE: DAINIPPON INK & CHEM KK[DNIN]

PRIORITY-DATA: 1983JP-0131886 (July 21, 1983)

PATENT-FAMILY:

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JP 60024990 A	February 7, 1985	N/A	006	N/A
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JP 60024990A	N/A	1983JP-0131886	July 21, 1983
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ABSTRACTED-PUB-NO: JP 60024990A

BASIC-ABSTRACT:

Resist pattern making method comprises (1) lithographic printing on the circuit board using resist ink which is curable by heat or active energy beam, (2) same pattern printing on the same position to remove pinholes and (3) curing printed pattern by exposing to heat or active energy beam. Pref. (2') standing of printed pattern is imposed between (2) and (3).

Conventional resist pattern making method is silk screen printing and by this method pattern resolution is 150-200 micron line width, so it cannot keep-up with recent patterns miniturisation. Lithographic printing can provide high resolution pattern of 30 micron line width, but has disadvantage of pinholes.

The improved lithographic printing method comprises process (1), (2), (2') and (3).

USE/ADVANTAGE - This resist pattern making method provides cheap and high resolution pattern.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: RESIST PATTERN PRODUCE LITHO PRINT CIRCUIT BOARD PINHOLE OVERPRINT
CURE

DERWENT-CLASS: G06 L03 P75 P83 V04

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TITLE: FORMING RESIST PATTERN

PUBN-DATE: February 7, 1985

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US-CL-CURRENT: 101/450.1

ABSTRACT:

PURPOSE: To enable to economically mass-produce a high-resolution resist pattern, by adopting a planographic printing system in place of a silk screen printing system.

CONSTITUTION: A printed pattern is provided on an objective substrate by a planographic printing system using a resist ink capable of being hardened by heat or active energy rays. The same pattern is further printed on the printed

pattern on the substrate, thereby removing holes such as pinholes and eye-holes present in the pattern. The printed pattern is hardened by heating or by exposing it to active energy rays, thereby producing a resist pattern on the substrate. A pattern forming method excellent in property for economical mass-production is the planographic printing system. Even in the case of using this system, the printed pattern produced by overlappingly printing the same pattern becomes a continuous film free of holes, so that the pattern can be used satisfactorily as a resist pattern.